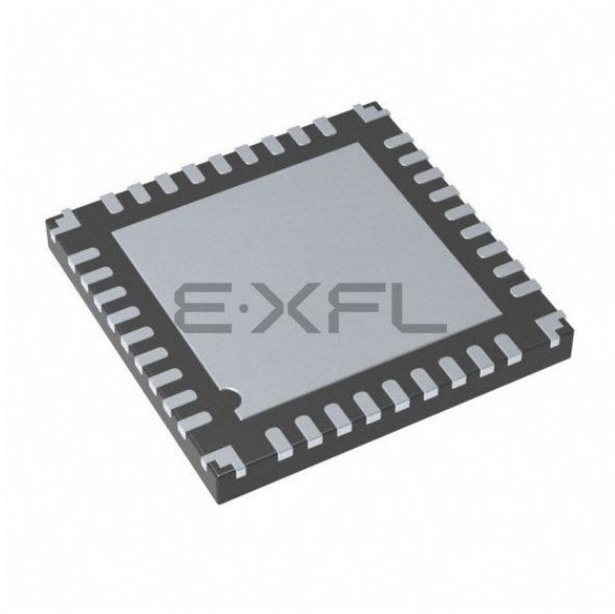
Microchip Technology - DSPIC33EV128GM103-I/M5 Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	25
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 13x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	36-UFQFN Exposed Pad
Supplier Device Package	36-UQFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ev128gm103-i-m5

FIGURE 3-1: dsPIC33EVXXXGM00X/10X FAMILY CPU BLOCK DIAGRAM

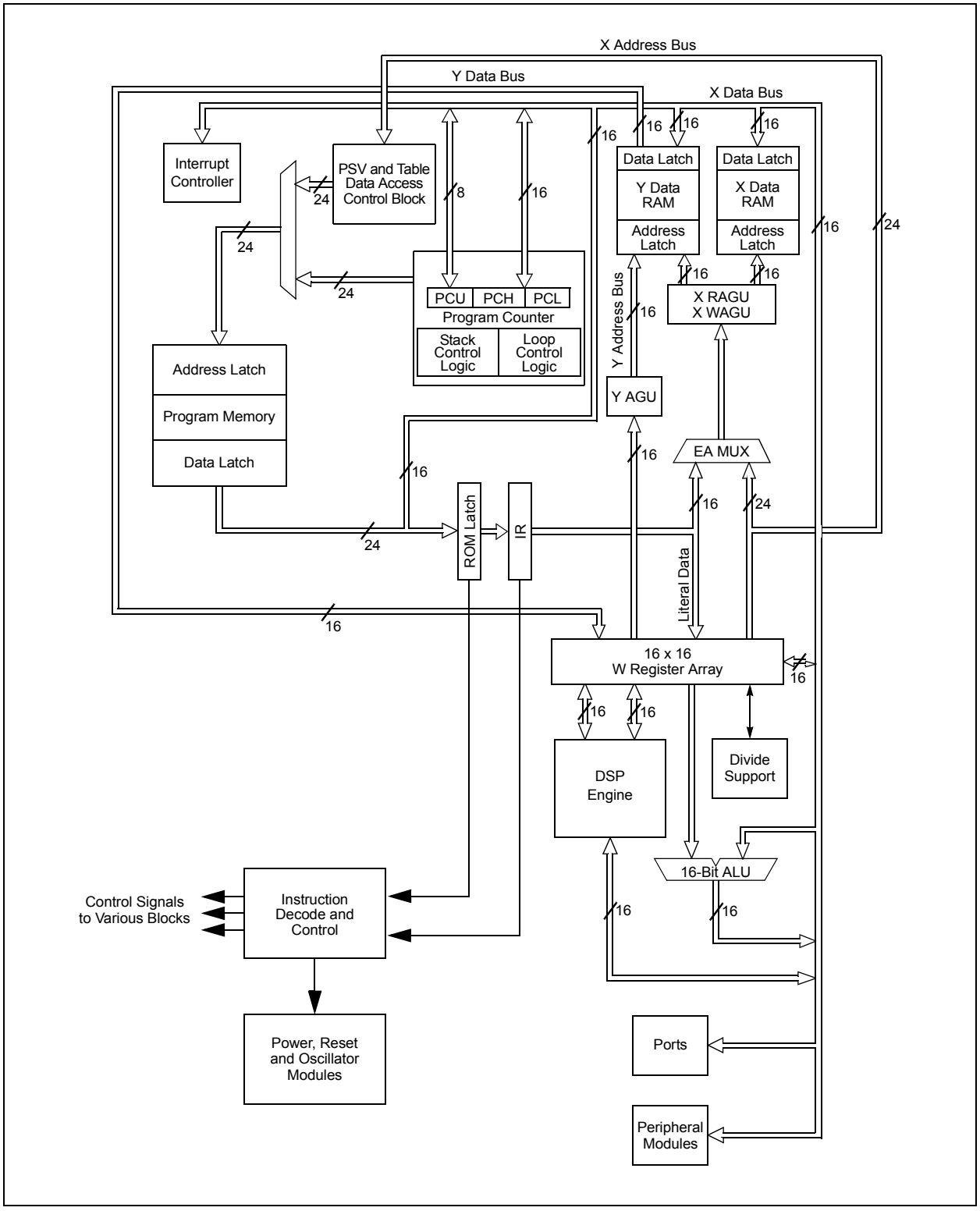

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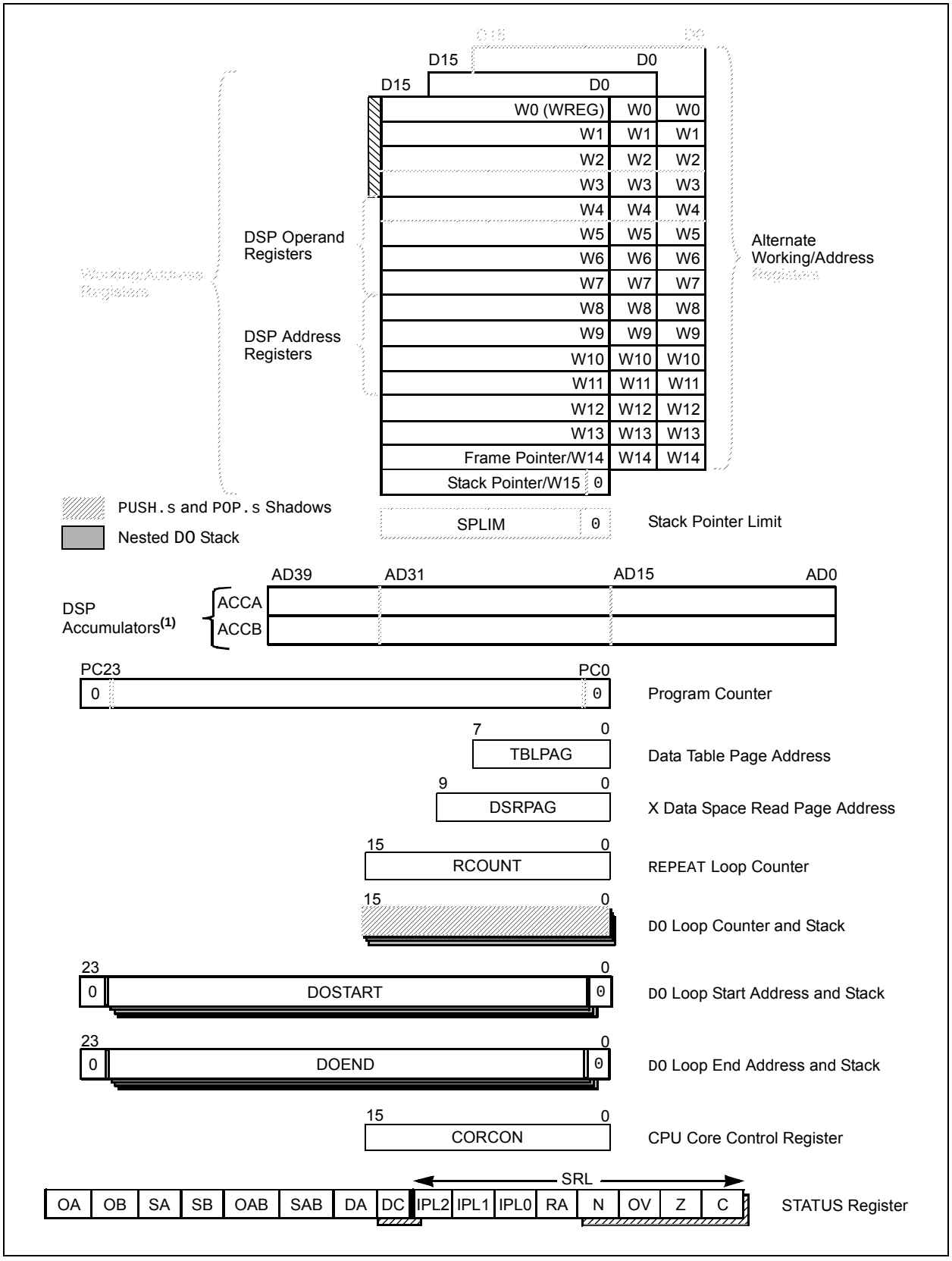
FIGURE 3-2: PROGRAMMER'S MODEL



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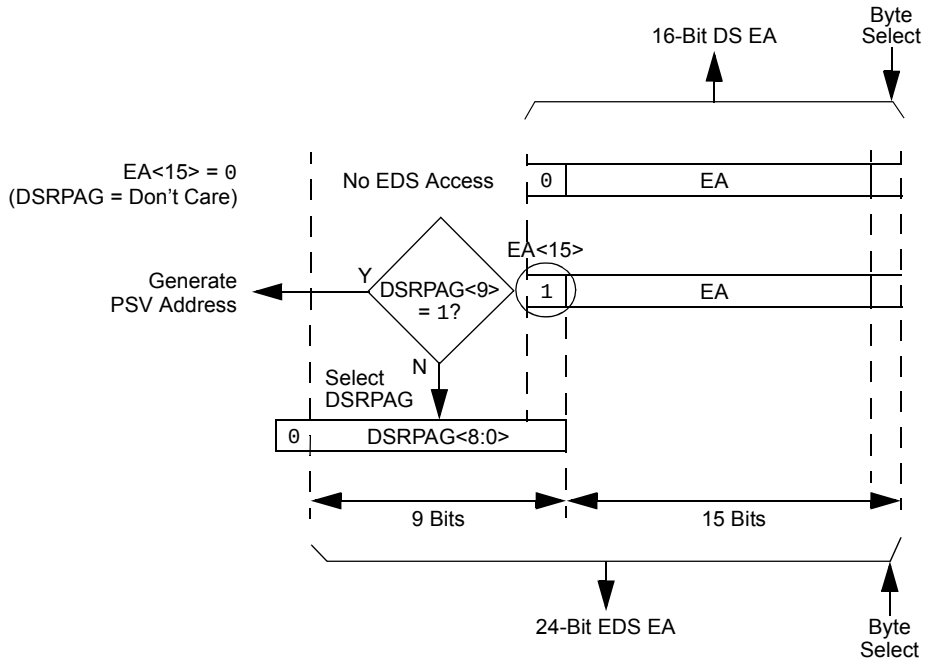
4.3.1 PAGED MEMORY SCHEME

The dsPIC33EVXXXGM00X/10X family architecture extends the available DS through a paging scheme, which allows the available DS to be accessed using MOV instructions in a linear fashion for pre- and post-modified Effective Addresses (EAs). The upper half of the Base Data Space address is used in conjunction with the Data Space Page registers, the 10-bit Data Space Read Page register (DSRPAG) or the 9-bit Data Space Write Page register (DSWPAG), to form an EDS address, or Program Space Visibility (PSV) address. The Data Space Page registers are located in the SFR space. Construction of the EDS address is shown in Figure 4-9 and Figure 4-10. When DSRPAG<9> = 0 and the base address bit, EA<15> = 1, the DSRPAG<8:0> bits are concatenated onto EA<14:0> to form the 24-bit EDS read address. Similarly, when the base address bit, EA<15> = 1, the DSWPAG<8:0> bits are concatenated onto EA<14:0> to form the 24-bit EDS write address.

FIGURE 4-9: EXTENDED DATA SPACE (EDS) READ ADDRESS GENERATION



Note: DS read access when DSRPAG = 0x000 will force an address error trap.

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8.0 DIRECT MEMORY ACCESS (DMA)

Note 1: This data sheet summarizes the features of the dsPIC33EVXXXGM00X/10X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Direct Memory Access (DMA)"** (DS70348) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The DMA Controller transfers data between Peripheral Data registers and Data Space SRAM. For the simplified DMA block diagram, refer to Figure 8-1.

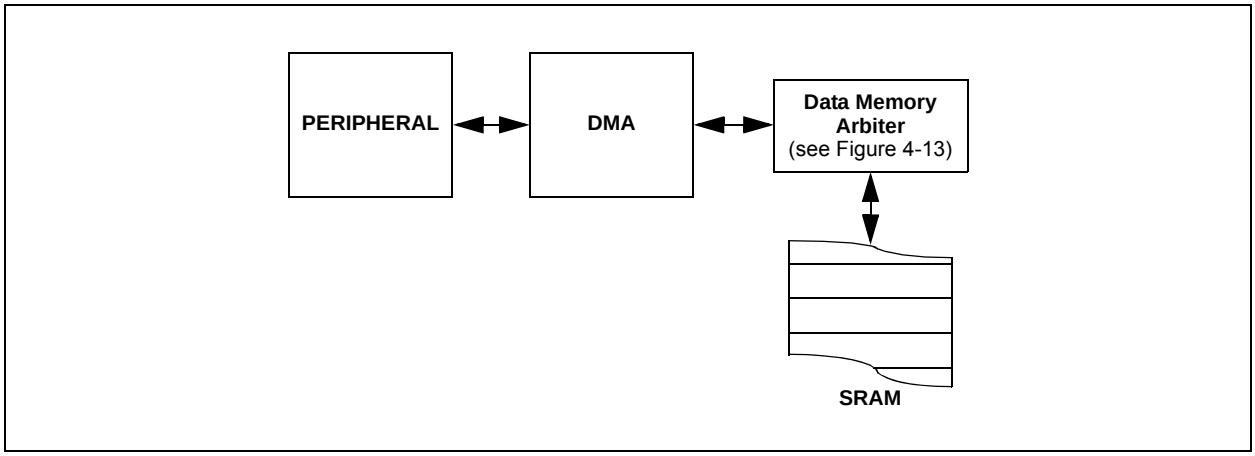
In addition, DMA can access the entire data memory space. The data memory bus arbiter is utilized when either the CPU or DMA attempts to access SRAM, resulting in potential DMA or CPU stalls.

The DMA Controller supports 4 independent channels. Each channel can be configured for transfers to or from selected peripherals. The peripherals supported by the DMA Controller include:

- CAN
- Analog-to-Digital Converter (ADC)
- Serial Peripheral Interface (SPI)
- UART
- Input Capture
- Output Compare

Refer to Table 8-1 for a complete list of supported peripherals.

FIGURE 8-1: PERIPHERAL TO DMA CONTROLLER



NOTES:

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REGISTER 17-15: FCLCONx: PWMx FAULT CURRENT-LIMIT CONTROL REGISTER(1) (CONTINUED)

bit 7-3 **FLTSRC<4:0>:** Fault Control Signal Source Select for PWM Generator x bits
11111 = Fault 32 **(default)**
11110 = Reserved
•
•
•
01100 = Op Amp/Comparator 5
01011 = Comparator 4
01010 = Op Amp/Comparator 3
01001 = Op Amp/Comparator 2
01000 = Op Amp/Comparator 1
00111 = Fault 8
00110 = Fault 7
00101 = Fault 6
00100 = Fault 5
00011 = Fault 4
00010 = Fault 3
00001 = Fault 2
00000 = Fault 1

bit 2 **FLTPOL:** Fault Polarity for PWM Generator x bit(2)
1 = The selected Fault source is active-low
0 = The selected Fault source is active-high

bit 1-0 **FLTMOD<1:0>:** Fault Mode for PWM Generator x bits
11 = Fault input is disabled
10 = Reserved
01 = The selected Fault source forces the PWMxH, PWMxL pins to FLTDAT<1:0> values (cycle)
00 = The selected Fault source forces the PWMxH, PWMxL pins to FLTDAT<1:0> values (latched condition)

Note 1: If the PWMLOCK Configuration bit (FDEVOPT<0>) is a '1', the FCLCONx register can only be written after the unlock sequence has been executed.

2: These bits should be changed only when PTEN = 0. Changing the clock selection during operation will yield unpredictable results.

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REGISTER 18-2: SPIxCON1: SPIx CONTROL REGISTER 1 (CONTINUED)

bit 4-2 **SPRE<2:0>:** Secondary Prescale bits (Master mode)(3)
111 = Secondary prescale 1:1
110 = Secondary prescale 2:1
•
•
•
000 = Secondary prescale 8:1

bit 1-0 **PPRE<1:0>:** Primary Prescale bits (Master mode)(3)
11 = Primary prescale 1:1
10 = Primary prescale 4:1
01 = Primary prescale 16:1
00 = Primary prescale 64:1

Note 1: The CKE bit is not used in Framed SPI modes. Program this bit to '0' for Framed SPI modes (FRMEN = 1).

2: This bit must be cleared when FRMEN = 1.

3: Do not set both primary and secondary prescalers to the value of 1:1.

NOTES:

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FIGURE 20-1: SENTx MODULE BLOCK DIAGRAM

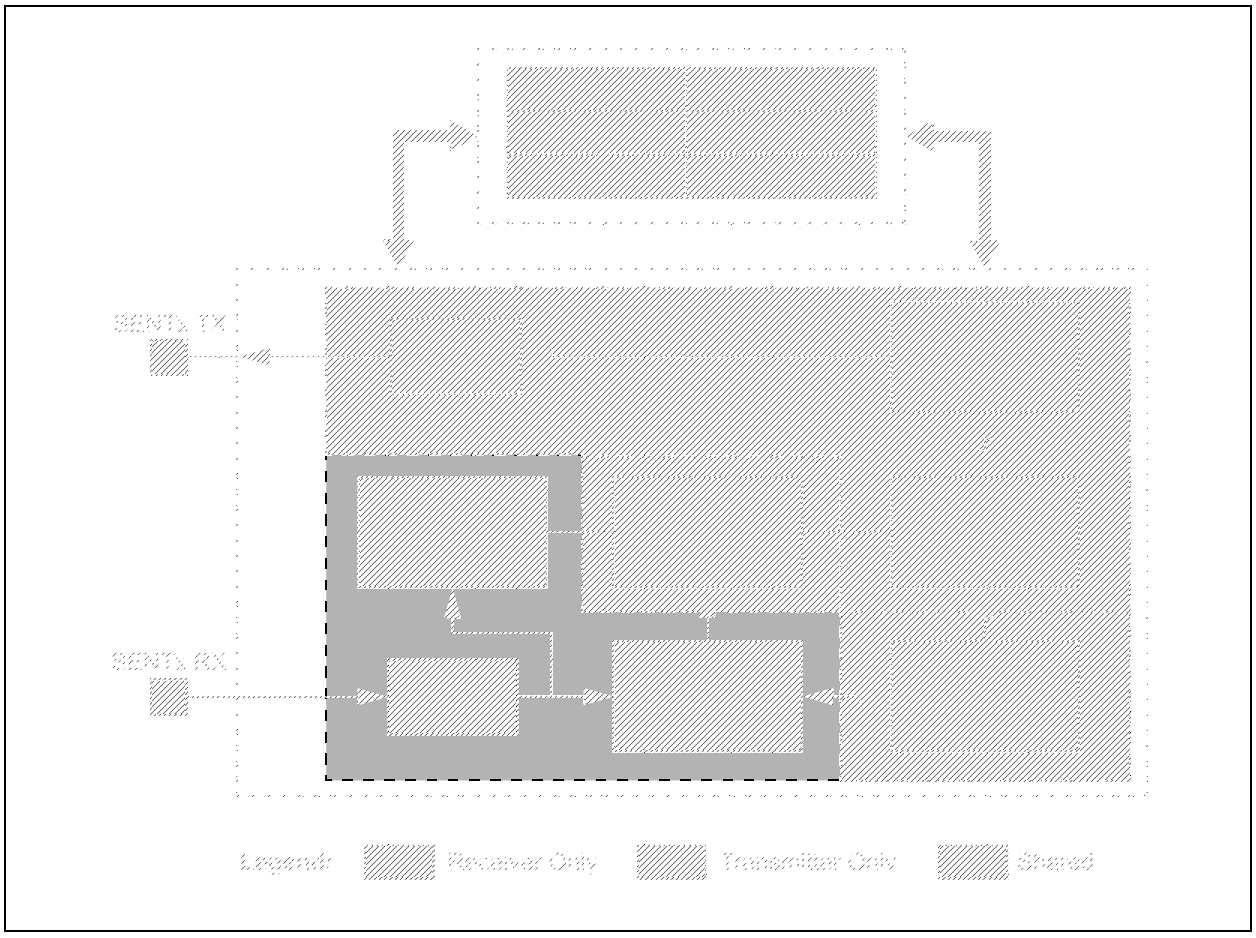
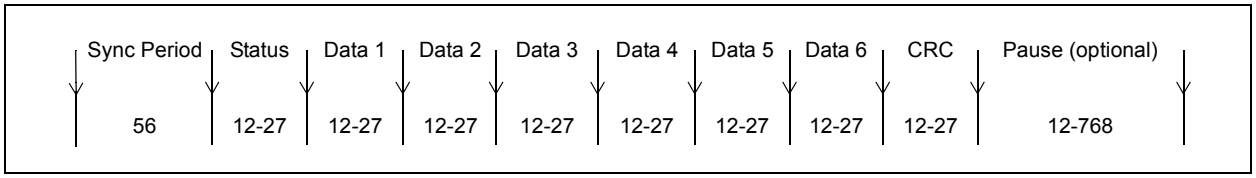


FIGURE 20-2: SENTx PROTOCOL DATA FRAMES



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NOTES:

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REGISTER 22-2: CxCTRL2: CANx CONTROL REGISTER 2

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R-0	R-0	R-0	R-0	R-0
—	—	—	DNCNT<4:0>				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-5 **Unimplemented:** Read as '0'

bit 4-0 **DNCNT<4:0>:** DeviceNet™ Filter Bit Number bits

10010-11111 = Invalid selection
10001 = Compare up to Data Byte 3, bit 6 with EID<17>
•
•
•
00001 = Compare up to Data Byte 1, bit 7 with EID<0>
00000 = Do not compare data bytes

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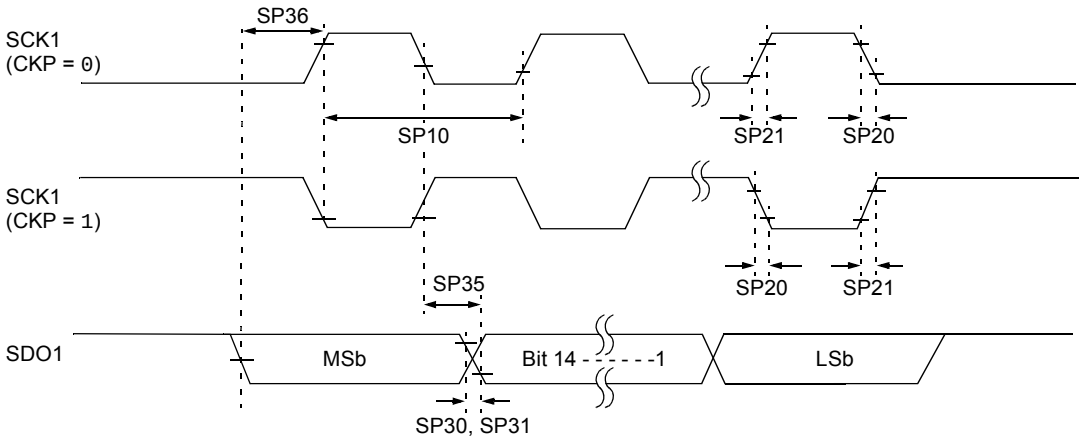
FIGURE 30-21: SPI1 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-39: SPI1 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP10	FscP	Maximum SCK1 Frequency	—	—	25	MHz	See **Note 3**
SP20	TscF	SCK1 Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP21	TscR	SCK1 Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdiV2scH, TdiV2scL	SDO1 Data Output Setup to First SCK1 Edge	20	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

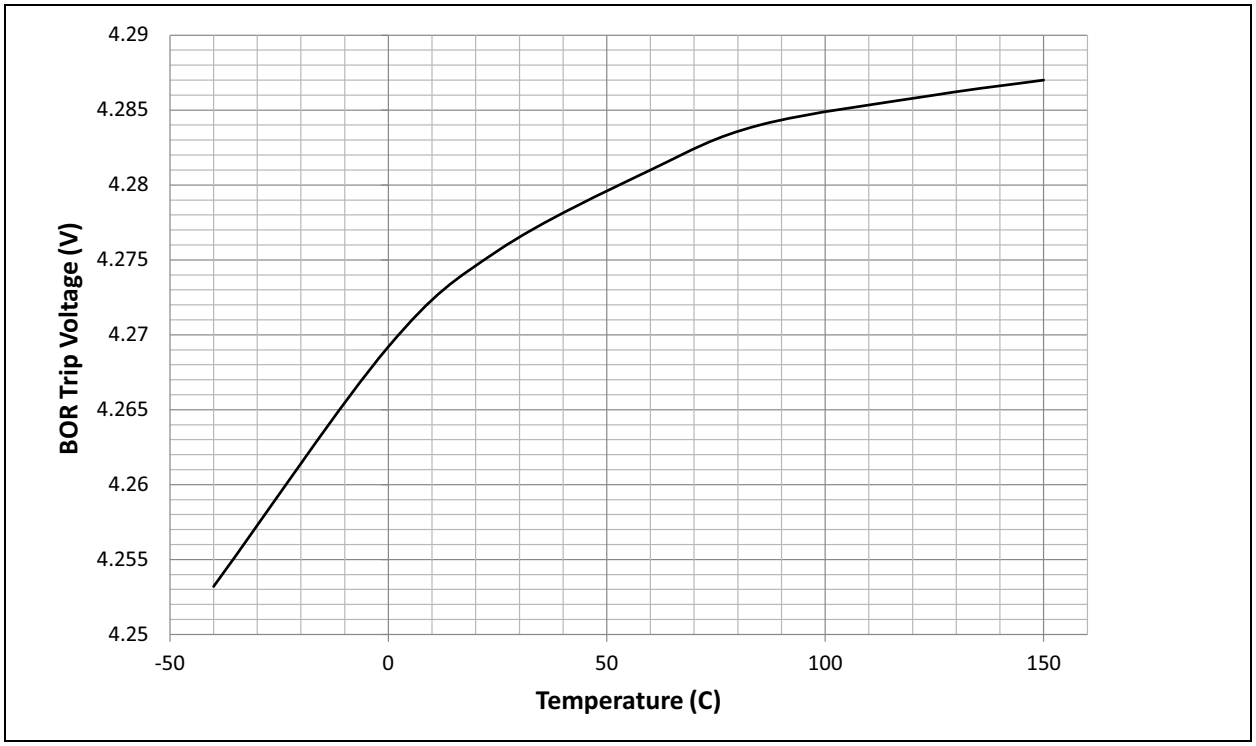
2: Data in “Typ.” column is at 5.0V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 40 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

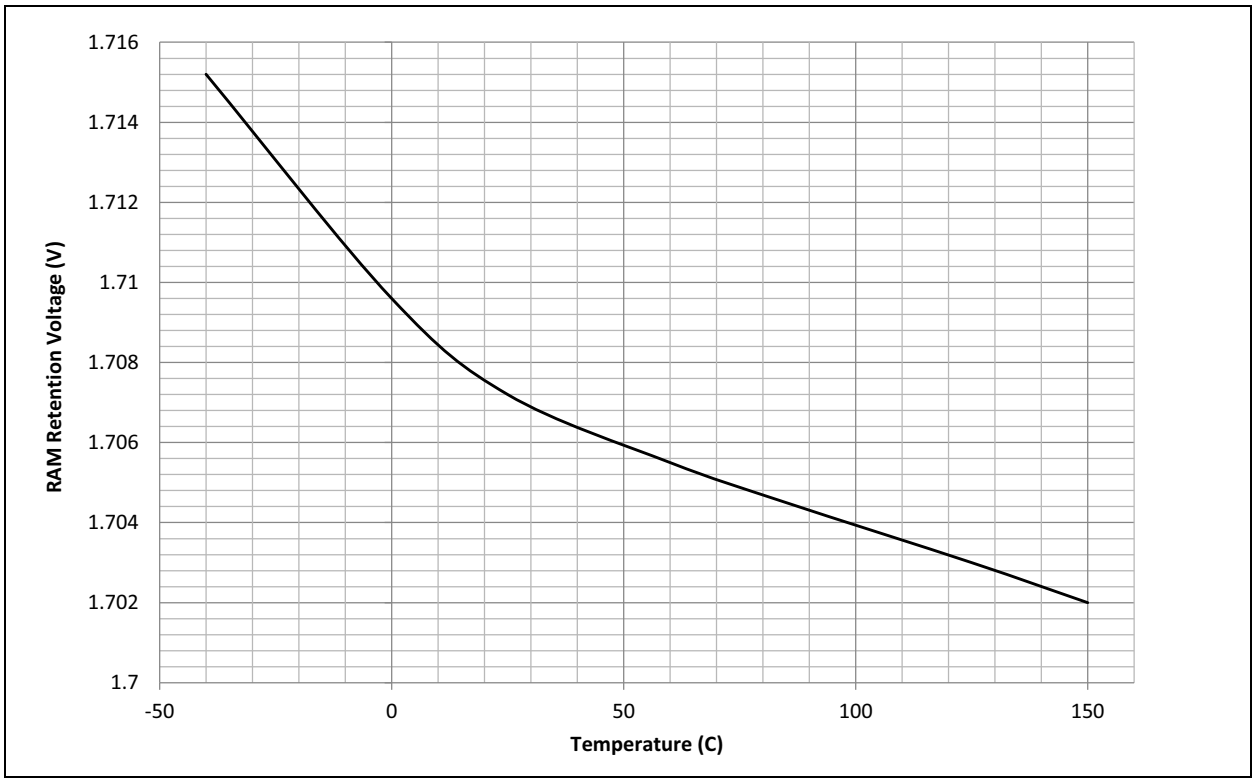
32.12 VBOR

FIGURE 32-35: TYPICAL BOR TRIP RANGE vs. TEMPERATURE



32.13 RAM Retention

FIGURE 32-36: TYPICAL RAM RETENTION VOLTAGE vs. TEMPERATURE



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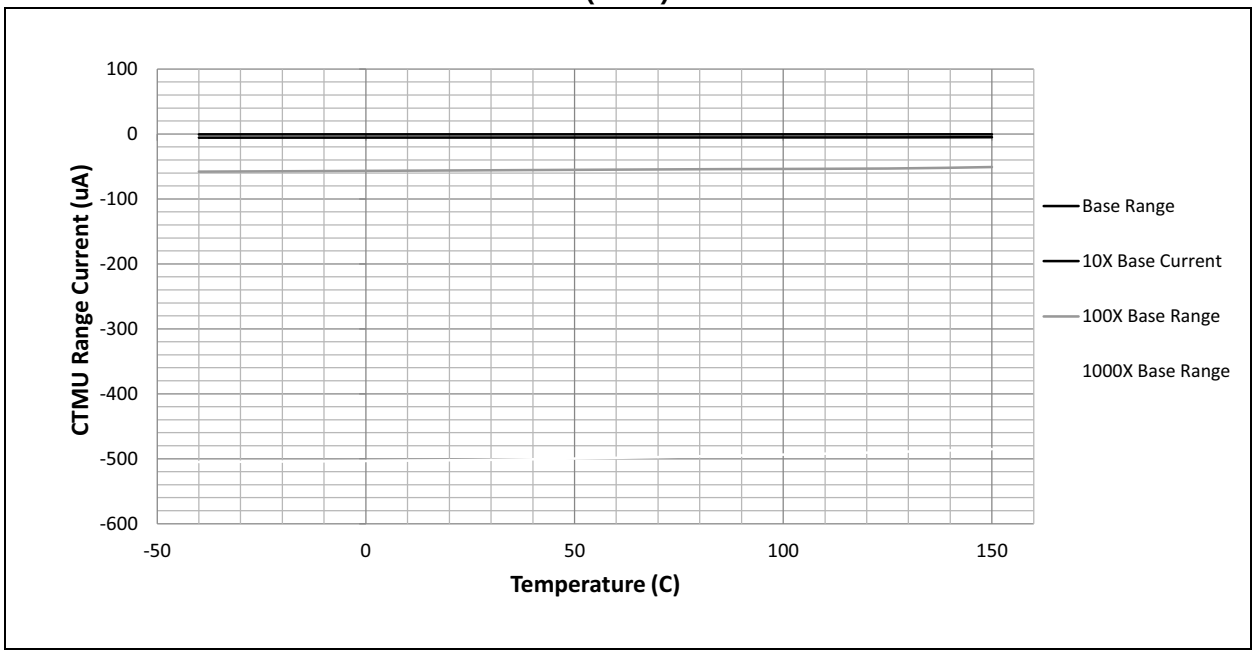
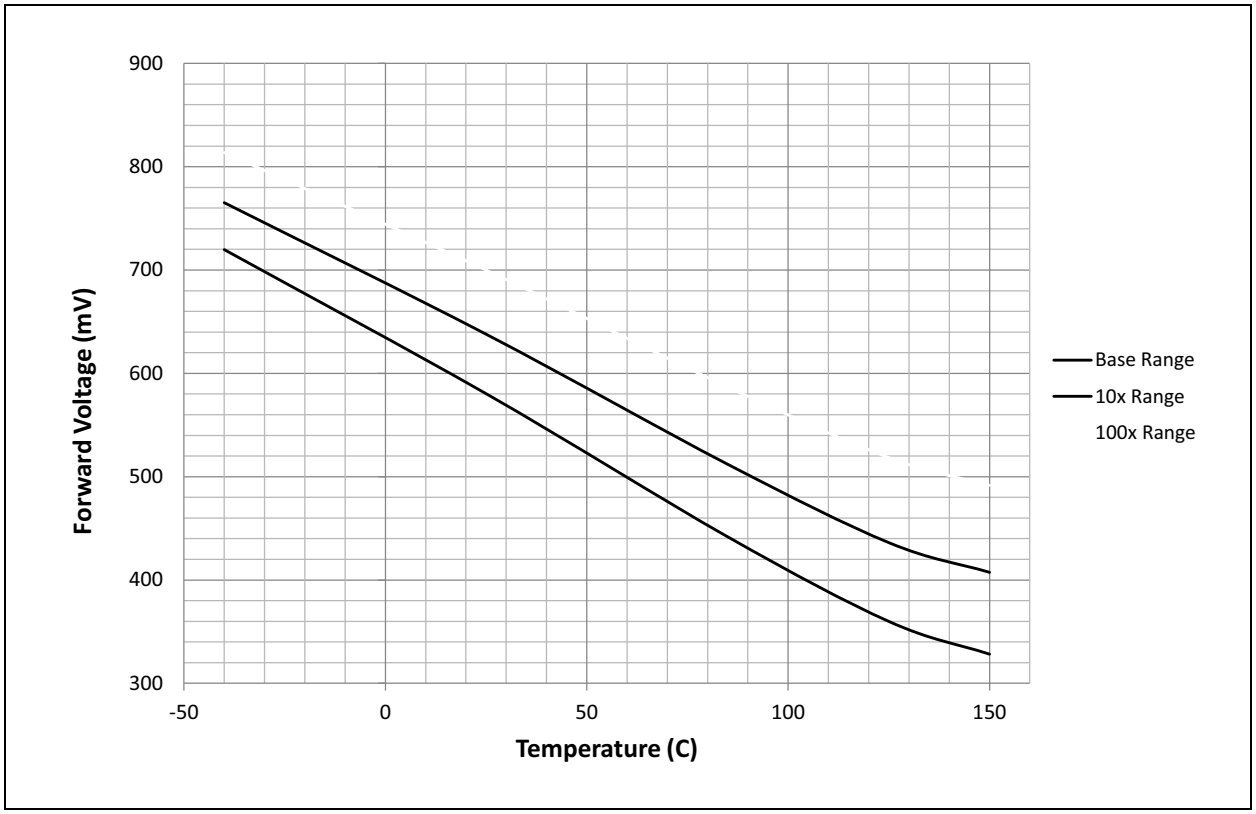
32.15 CTMU Current vs. Temperature

FIGURE 32-39: TYPICAL CTMU CURRENT (IRNG) vs. TEMPERATURE



32.16 CTMU Temperature Forward Diode

FIGURE 32-40: TYPICAL CTMU TEMPERATURE DIODE FORWARD VOLTAGE vs. TEMPERATURE



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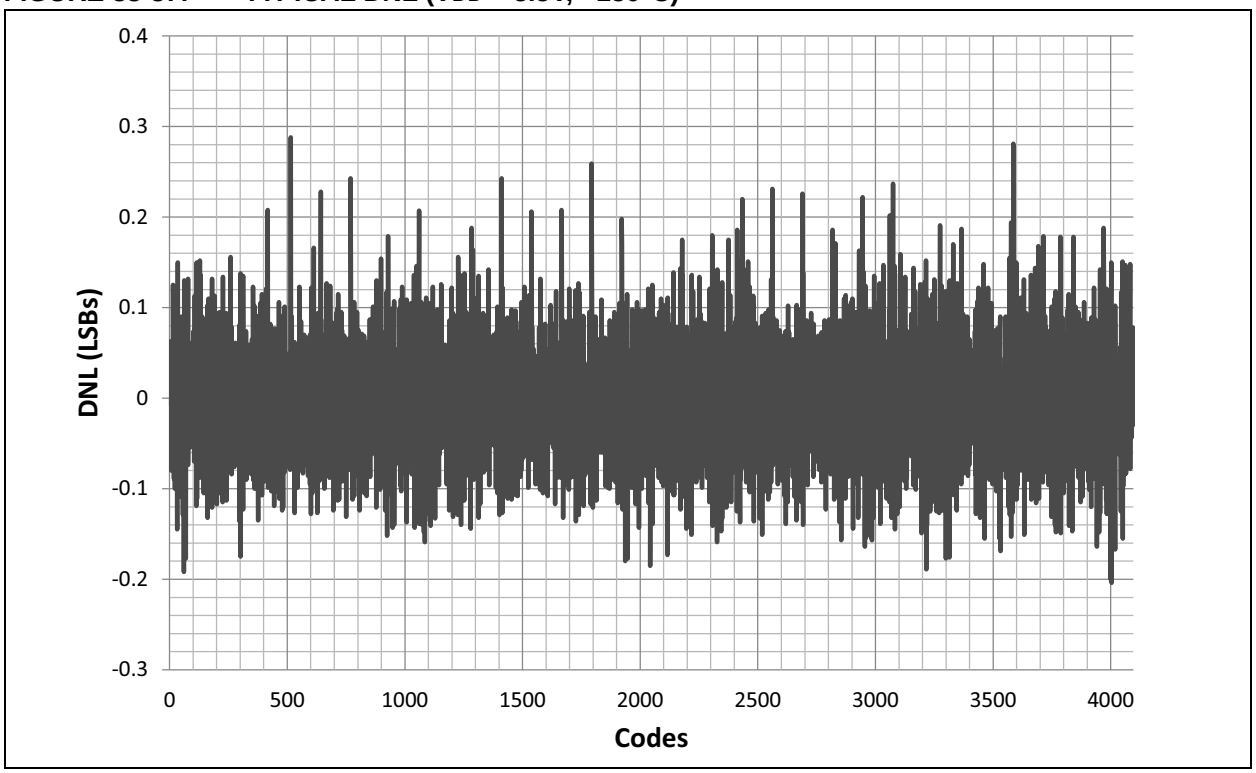
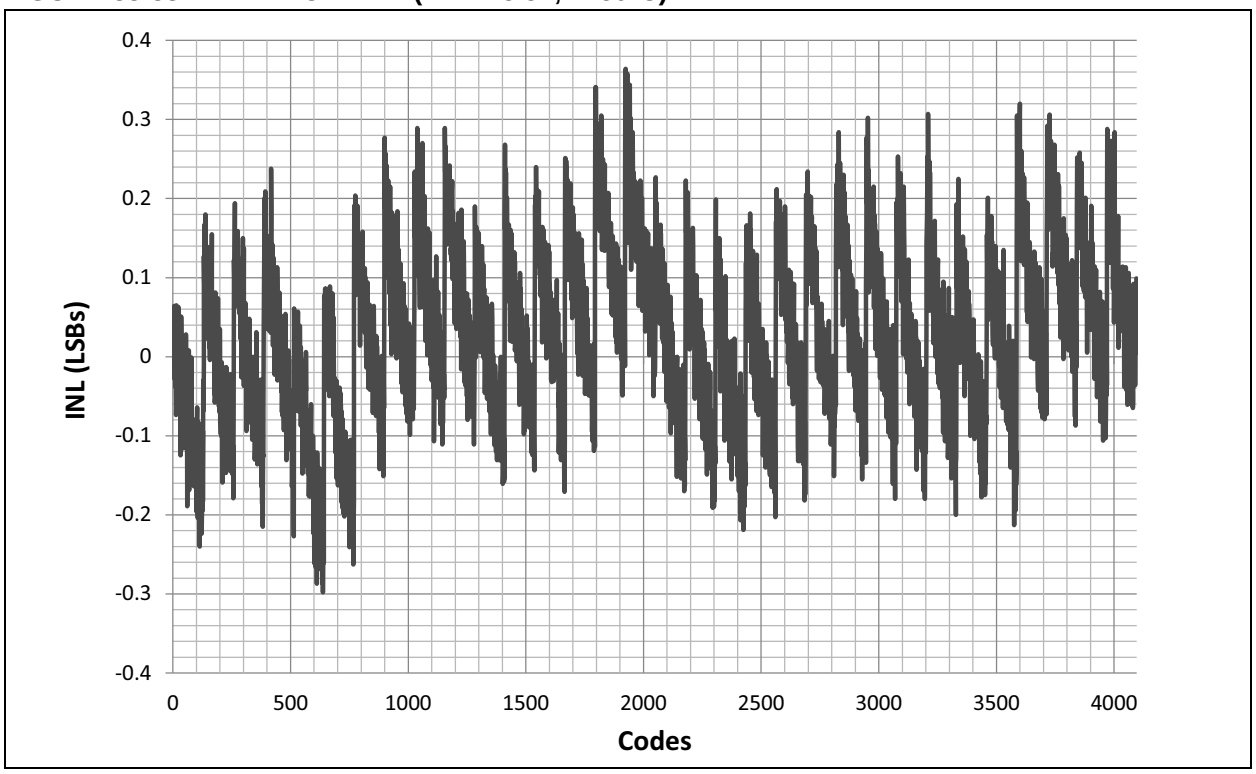
33.17 ADC DNL

FIGURE 33-37: TYPICAL DNL (V_{DD} = 5.5V, +150°C)



33.18 ADC INL

FIGURE 33-38: TYPICAL INL (V_{DD} = 5.5V, +150°C)



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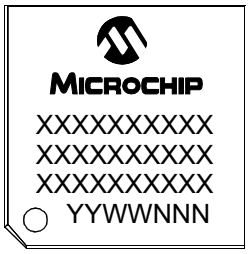
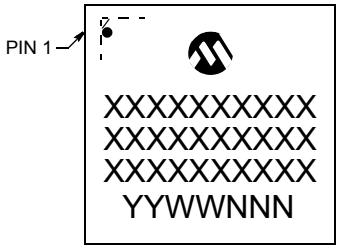
34.1 Package Marking Information (Continued)

44-Lead TQFP (10x10x1 mm)

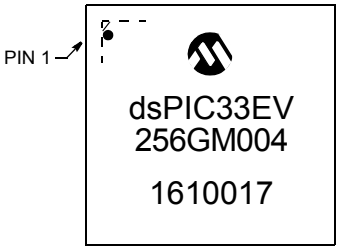


Example

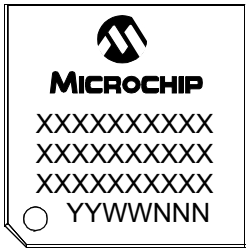
44-Lead QFN (8x8 mm)



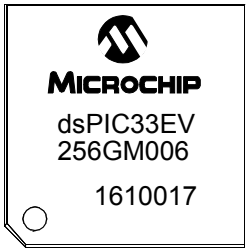
Example



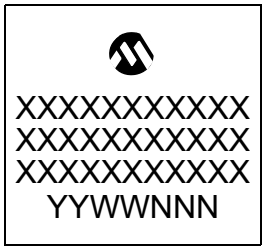
64-Lead TQFP (10x10x1 mm)



Example



64-Lead QFN (9x9x0.9 mm)



Example

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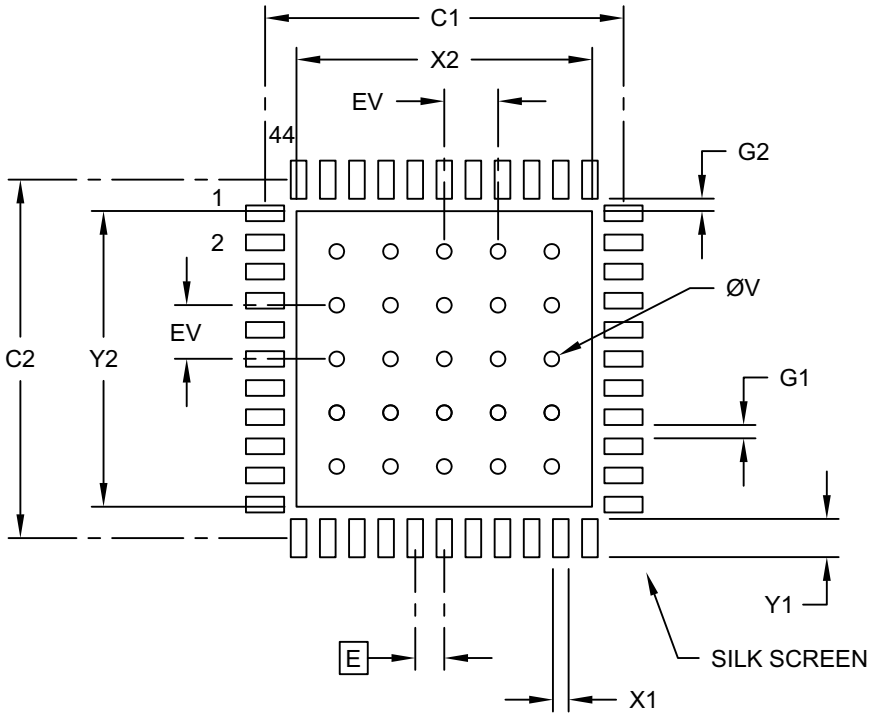
44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN or VQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Optional Center Pad Width	X2			6.60
Optional Center Pad Length	Y2			6.60
Contact Pad Spacing	C1		8.00	
Contact Pad Spacing	C2		8.00	
Contact Pad Width (X44)	X1			0.35
Contact Pad Length (X44)	Y1			0.85
Contact Pad to Contact Pad (X40)	G1	0.30		
Contact Pad to Center Pad (X44)	G2	0.28		
Thermal Via Diameter	V		0.33	
Thermal Via Pitch	EV		1.20	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

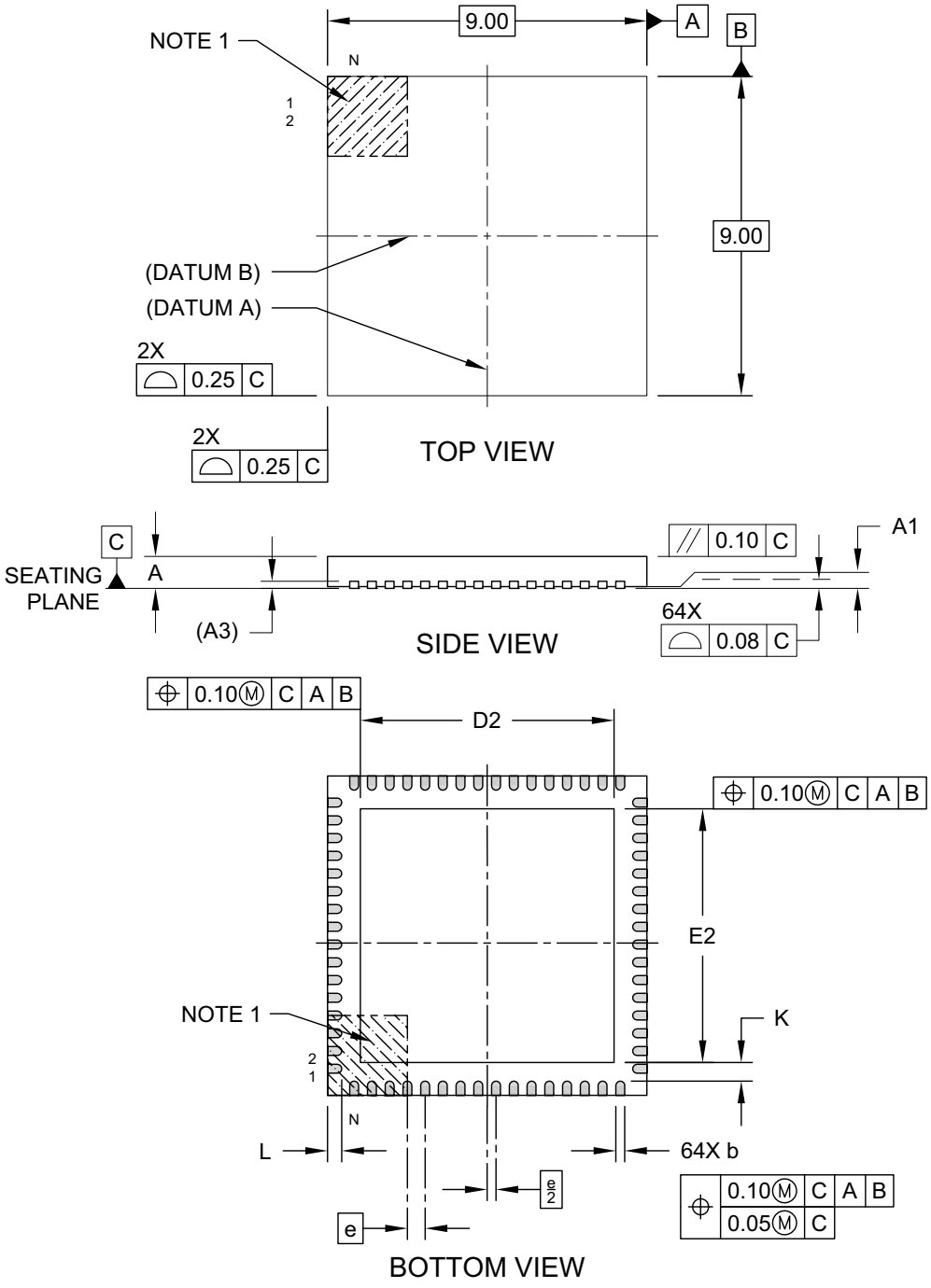
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing No. C04-2103C

64-Lead Very Thin Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body [VQFN]
With 7.15 x 7.15 Exposed Pad [Also called QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-149D [MR] Sheet 1 of 2

Revision E (September 2016)

This revision incorporates the following updates:

- Sections:
  - Added new **Section 32.0 “Characteristics for Industrial/Extended Temperature Devices (-40°C to +125°C)”** and **Section 33.0 “Characteristics for High-Temperature Devices (+150°C)”**.
  - Updated the **Qualification and Class B Support** section.
  - Updated **Section 27.6 “In-Circuit Serial Programming”**.
  - Updated **Section 34.0 “Packaging Information”** with the addition of the 28-Lead SSOP package information and new packaging diagram revisions.
  - Updated the **“Product Identification System”** section with the addition of the 28-Lead SSOP package.
- Figures:
  - Updated Figure 4-6.
- Registers:
  - Updated Register 25-2, Register 25-3, Register 27-1 and Register 27-2.
- Tables:
  - Updated Table 30-7, Table 30-9, Table 30-39, Table 30-40, Table 30-41, Table 30-42, Table 30-43, Table 30-44 and Table 30-45.

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